

REMARKS

Applicants are adding new claim 21 to the application, for further definition of aspects of the present invention. Claim 21 defines a method of fabricating a semiconductor device, including, inter alia, affixing a protective tape to a first face of the wafer and thinning the wafer from the second face; affixing respectively a die bonding film to the second face of the wafer and a dicing tape over this die bonding film on the second face; peeling off a protective film from the first face of the wafer; and dicing the wafer. As will be shown in the following, it is respectfully submitted that claim 21 a generic claim, to the species listed as Species 1-3 on page 2 of the Office Action mailed February 14, 2005, particularly Species 1 and 3.

In connection with new claim 21, note, Fig. 1; and see also the description on pages 9-16 of the Substitute Specification submitted in the Amendment filed January 6, 2004.

The election-of-species requirement set forth on page 2 of the Office Action mailed February 14, 2005, is noted. Consistent with requirements therein, Applicants respectfully elect Species 1, which the Examiner contends pertains to a method including grinding a second face of a wafer and thereafter fixing a die bonding film and affixing a dicing tape to the second face of the wafer, in sequential order. The Examiner indicates that claims 1-13 read on this elected species.

Applicants respectfully traverse the conclusion by the Examiner that the original claims fall within three separate species. The Examiner contends that claims 1-13 pertain to a method including grinding a second face of a wafer and "thereafter" affixing a die bonding film and affixing a dicing tape to a

second face of a wafer in sequential order; and Species 3 (claims 18-20) pertains “to a method including after grinding”.

However, it is respectfully submitted that Species 1 also pertains to a method “including after grinding”. That is, even as Species 1 has been interpreted by the Examiner, it includes grinding a second face of a wafer and thereafter affixing a die bonding film and affixing dicing tape to a second face of the wafer in sequential order. Clearly, Species 1 includes processing “after grinding”, as alleged by the Examiner in connection with Species 3. Thus, it is respectfully submitted that at least Species 1 and Species 3 claims should be considered together, and that, designating this group species as Species 1a, it is respectfully submitted that claims 1-13 and 18-20 read on this grouped species.

Furthermore, note that claim 18 recites the step of cutting the die bonding film along an outer periphery of the wafer (see step (f)); see also claim 13, dependent on claim 1, and reciting (in step d3) cutting the die bonding film along an outer periphery of the wafer. Note also step (d) of claim 14, reciting the step of cutting the die bonding along an outer periphery of the wafer. It is respectfully submitted that claim 18 recites steps which are a combination of claim 1 and claim 14; that claim 13 also recites steps which are a combination of claims 1 and 14 and that it would not constituted an undue burden from the Examiner to consider to subject matter of claims 14-17 in the present application, together with the subject matter of claims 1-13 and 18-20.

In addition, attention is respectfully directed to newly added claim 21, defining a method of fabricating a semiconductor device, including steps of

affixing various tapes to first and second faces of a wafer and thinning the wafer from the second face, peeling off a protective tape from the first face and dicing the wafer. It is respectfully submitted that claim 21 is generic to each of Species 1-3 as listed on page 2 of the Office Action mailed February 14, 2005; and that upon allowance of claim 21, the non-elected species should be rejoined in the above-identified application and allowed therein, even if the election-of-species requirement is maintained.

In any event, for providing a complete response to the Office Action mailed February 14, 2005, Applicants respectfully elect the Species 1 claims, which the Examiner contends are claims 1-13, for prosecution on the merits in the present application. It is respectfully submitted that newly added claim 21 also reads on Species 1, and should be considered on the merits in the above-identified application.

In addition, Applicants respectfully submit that the Species 3 claims, which the Examiner contends is a separate species from Species 1, should be included with the Species 1, and that all of claims 1-13 and 18-21 should be considered on the merits in the above-identified application.

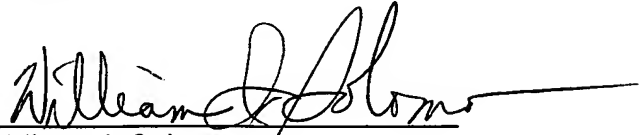
Furthermore, upon allowance of claim 21, it is respectfully submitted that claims 14-17 should be rejoined in the above-identified application and allowed therein.

Continued examination of the above-identified application in due course is respectfully requested.

To the extent necessary, Applicants petition for an extension of time under 37 CFR §1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to

Deposit Account No. 01-2135 (Case No. 501.43182X00) and please credit any excess fees to such deposit account.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "William I. Solomon", with a long horizontal flourish extending to the right.

William I. Solomon
Registration No. 28,565
ANTONELLI, TERRY, STOUT & KRAUS, LLP

WIS/kmh

Attachments